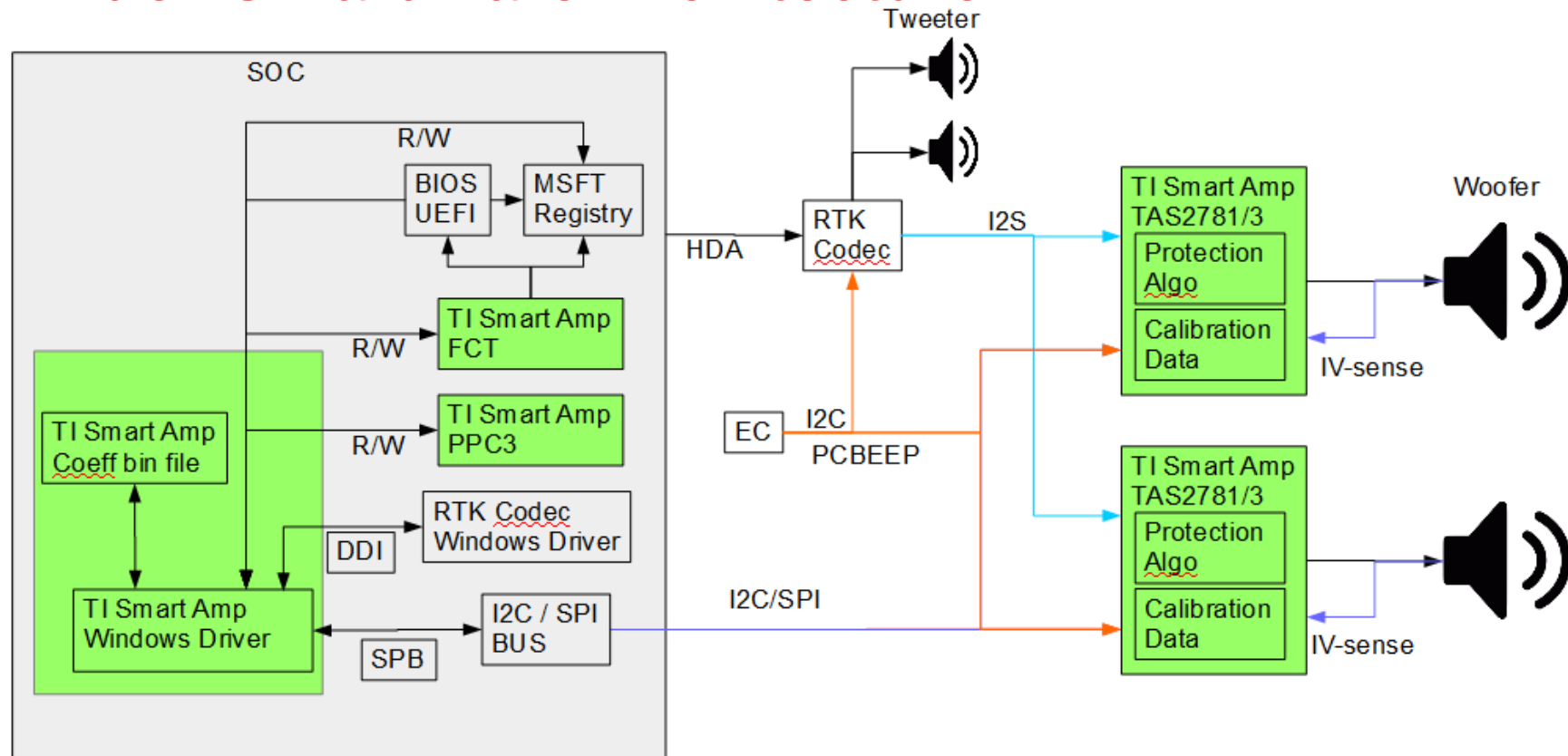


TAS2781/3 – FCT (using windows driver)

Windows Hardware Architecture

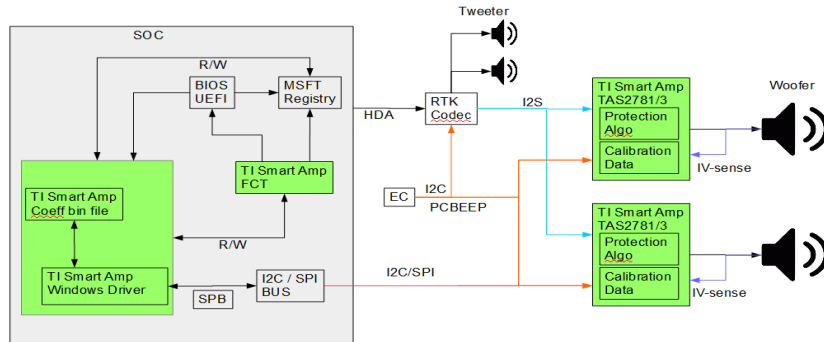


Independent FCT Tool

- TAS2781/3 is integrated device and protection algorithm runs on TAS2781/3 internal DSP.
- FCT process contains below tasks
 - Calculating the calibration data of speaker connected with the device at factory setup.(FCT App)
 - Saving the calibrated data in a persistent non volatile memory during factory. (FCT App)
 - Fetching calibrated data from persistent memory during boot up and programming TAS2781/3 DSP with calibrated data. (Windows Driver)
 - Calibrated data generated for TAS2781/3 is Re, rms_pow, t_limit.
 - Re : Speaker Re
 - rms_pow : Total RMS power coefficient
 - t_limit : Delta temperature limit coefficient
 - Data Stored in the persistent memory will be Re, rms_pow, t_limit, R0_low, Inverse R0.
 - R0 low & inverse R0 will be calculated using calibrated Re
 - Each calibration parameter would need 4 byte data and hence we would need 20 bytes of calibration data per channel.

TAS2781/3 FCT Process using UEFI/windows registry Memory

- FCT app will run on Intel/AMD processor during factory setup. (this is done only once at Factory)
- Calibrated data will be stored in dual storage of BIOS & windows registry edit.
- Window's driver will read the calibration data from windows registry during device bootup and configure the TAS2781/3 AMP with calibration data. Calibration data should also be downloaded every time firmware binary is loaded (e.g new configuration profile like music/voice etc to be loaded). So this means that firmware configuration is changed, download calibration data must be downloaded.
- If calibrated data is not available at win registry, windows driver will read calibrated data from BIOS and copy it to win registry and also program TAS2781/3 DSP.
- Location of TAS2781/3 where calibration data to be stored :



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Calibration Data	Book	Page	Reg
Re	0x00	0x17	0x74
Re_Low	0x00	0x18	0x0c
INV_RE	0x00	0x18	0x14
RMS_Pow	0x00	0x13	0x70
T_Limit	0x00	0x18	0x7c

Windows Driver GUID to access UEFI memory

- FCT app will save the calibration data at UEFI Memory as Key/Value Pair.
- GUID will be required to access UEFI Memory for read/write as per below UEFI API requirements. Windows driver GUID can be used to access UEFI Memory by FCT App.
- . Sample code as below

```
int write_to_uefi(int re_value, bool right)
{
    DWORD dwErr = ERROR_SUCCESS;
    INT32 data = re_value;
    BOOL success = false;

    if (right) {
        success = SetFirmwareEnvironmentVariable(
            L"Re_R",
            L"{9A44A769-1A51-464A-A54B-1A4084BF370B}",
            &data,
            sizeof(data)
        );
    }
}
```

```
int write_kvpair_uefi(wchar_t* key, int32_t value)
{
    DWORD dwErr = ERROR_SUCCESS;
    INT32 data = value;
    BOOL success = false;

    if (!key)
        dwErr = ERROR_INVALID_DATA;

    if (key)
    {
        success = SetFirmwareEnvironmentVariable(
            key,
            L"{9A44A769-1A51-464A-A54B-1A4084BF370B}",
            &data,
            sizeof(data)
        );
    }
}
```

- Accessing to UEFI would need special privilege permissions to read/write to this memory.
- In TI SmartAMP driver, below is default GUID for save FCT data in BIOS:
{0x1f52d2a1, 0xbb3a, 0x457d, {0xbc, 0x09, 0x43, 0xa3, 0xf4, 0x31, 0x0a, 0x92}}, Name = L"CALI_DATA", 128 Bytes.

- For HP & DELL machine.
DEFINE_GUID(GUID_HP_FCT_READ, 0x02f9af02, 0x7734, 0x4233, 0xb4, 0x3d, 0x93, 0xfe, 0x5a, 0xa3, 0x5d, 0xb3);
DEFINE_GUID(GUID_DELL_FCT_READ, 0xcc92382d, 0x6337, 0x41cb, 0xa8, 0x8b, 0x8e, 0xce, 0x74, 0x91, 0xea, 0x9f);

TI Information – Selective Disclosure

Details about the Calibration data for TAS2781/3

TAS2781/3 calibration data : total 20 byte of calibration data will be generated by each channel

Below data is generated during FCT process by each AMP

- Re : Speaker Re (4 Byte)
- rms_pow : Total RMS power coefficient (4 Byte)
- t_limit : Delta temperature limit coefficient (4 Byte)

Below data is calculated by FCT App using calibrated data (Calibrated Re) of each AMP

- Re_low (4 Byte)
- Inverse_Re (4 Byte)
- TAS2781/3 is Integrated device with protection algorithm being run on TAS2781/3 DSP.
- TAS2781/3 DSP algorithm expect FCT App to provide and program each AMP with Re, rms_pow, t_limit , Re_low and Inverse_R0.
- TAS2781/3 can retain these values in TAS2781/3 DSP even during device shutdown and hence these values need to be updated only during device boot-up time.
- UFEI would need to store all these values for each speaker present in system so values need to be stored in case of stereo use case as below:

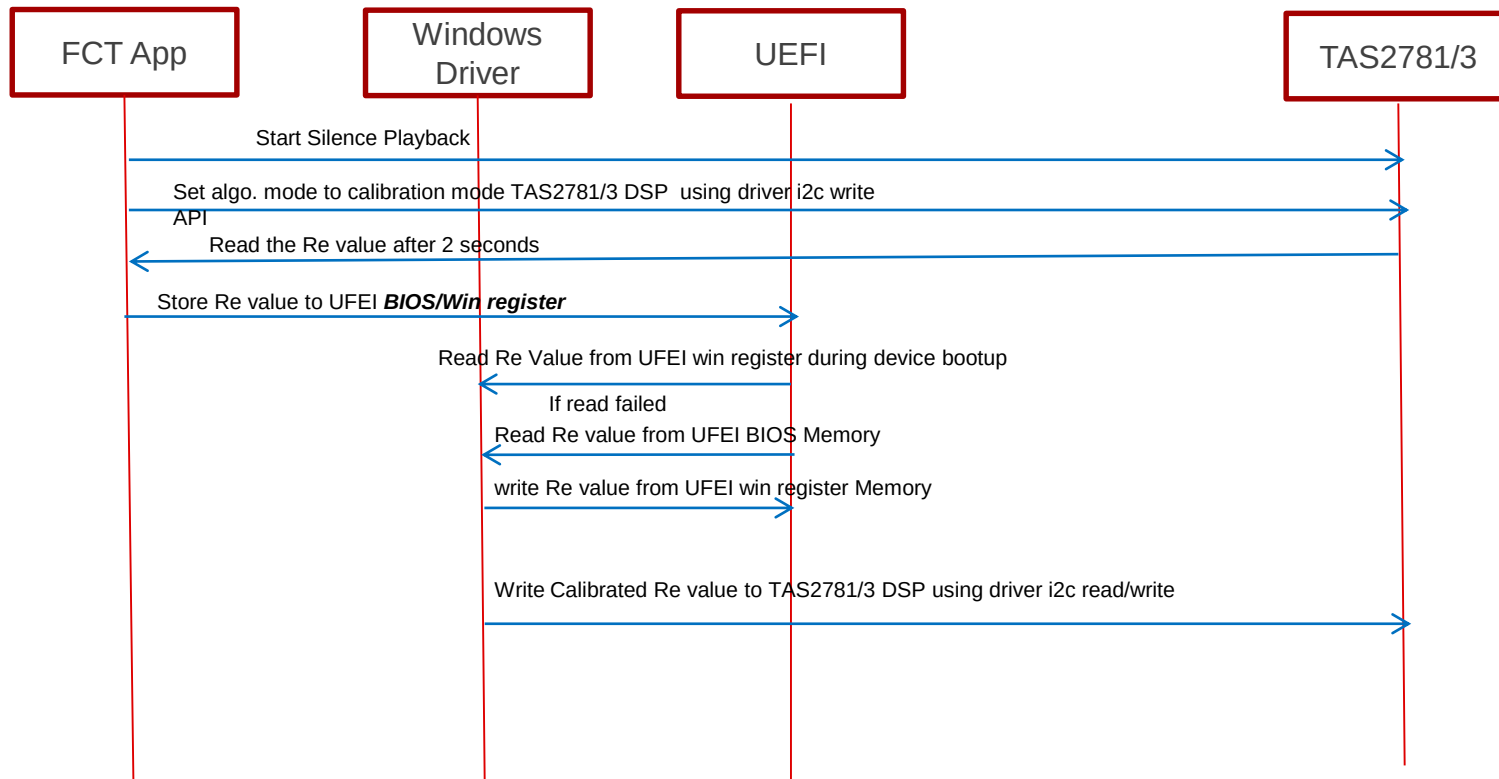
Left Speaker:

1. Re_L (4 bytes)
2. Rms_power_L (4 bytes)
3. T_limit_L (4 bytes)
4. Re_Low_L (4 bytes)
5. Inverse_Re_L (4 bytes)

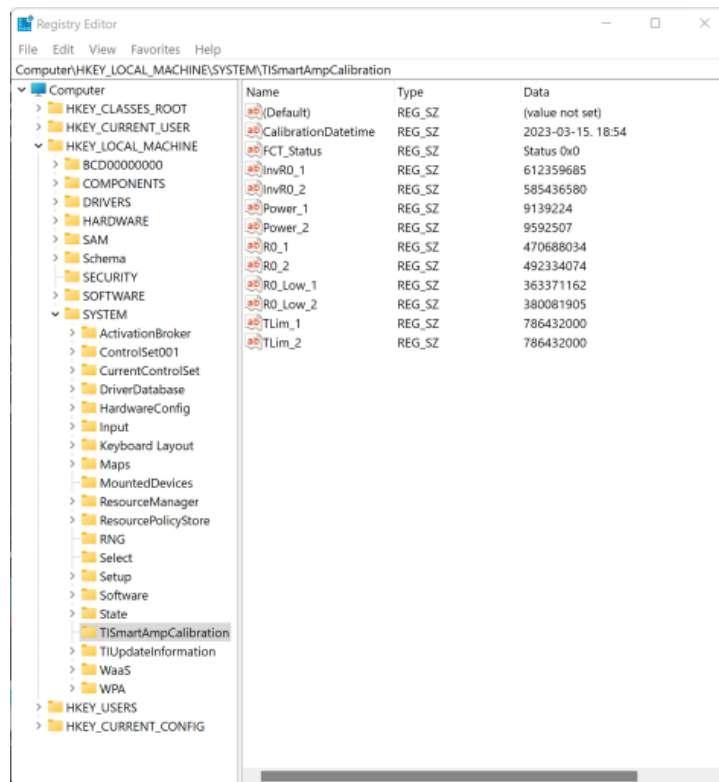
Right Speaker:

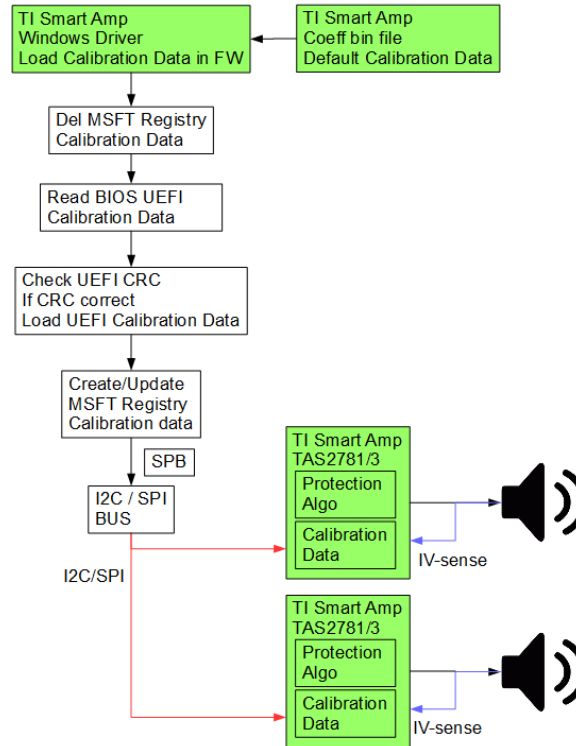
1. Re_R (4 bytes)
2. Rms_power_R (4 bytes)
3. T_limit_R (4 bytes)
4. Re_Low_R (4 bytes)
5. Inverse_Re_R (4 bytes)

Process Flow for UEFI Based Approach



How Calibration data will be stored





Factory Line Calibration

Smart Amp | Factory Line Calibration

- Factory Line Calibration is required for baselining the speaker DC resistance
- At factory floor, the DC resistance of the speaker is measured at ambient temperature using a low level signal. This value is then used to detect the temperature rise of the speaker relative to the factory line ambient temperature
- The factory line calibration compensates for speaker-to-speaker variation of DC resistance.

System Impact (without FTC)

- Let us consider a speaker spread of Rdc variance of $\pm 5\%$ for a $4\ \Omega$ load.
- Let us assume the Tmax to be 100 degC and Talpha (thermal coefficient of copper) as 0.00345.

	Rdc	Talpha	Tmax	Rdc' @ Tmax	Actual Tmax @ Rdc
Rdc	4	0.00345	100	5.104	80
Rdc + 5%	4.2	0.00345	100	5.3592	62.38
Rdc – 5%	3.8	0.00345	100	4.8488	99.46

- As can be seen for speaker with -5% variance although the actual Tmax is 100 degC it settles at around 99 degC which is dangerous. To mitigate this the Tmax will need to be set to (99 – 80 degC) however this can further reduce the settling temperature of speaker with +5% variance. This can result in each speaker sounding at different SPL levels.

- $R = R_{\text{ref}} * [1 + \alpha * (T - T_{\text{ref}})] = R_{\text{ref}} * [1 + \alpha * \Delta T]$
 - R = conductor resistance at temperature “T”
 - R_{ref} = conductor resistance at reference temperature “ T_{ref} ”, usually is 20°C
 - α = Temperature coefficient of resistance for conductor material, copper is 0.0033K⁻¹.
 - T = Conductor temperature in degree Celsius.
 - T_{ref} = Reference temperature that α is specified at for the conductor material.

- Calibration data structure:
ChipID (2781, 4 bytes)
Device-Number (4 bytes)
TimeStamp of Calibration (4 bytes)
for (i = 0; i < Device-Number; i++) {
Device index (4bytes)
Calibrated Data of Device #i (20 bytes)
}
CRC (4 bytes)

Total size = 16+24*dev_num;
40, 64, 88, 112, ...